- Four Independent Drivers and ReceiversLoopback Mode Functionally Self Tests
- Loopback Mode Functionally Self Tests
 Drivers and Receivers Without
 Disconnection From Line
- Driver Slew Rate Controlled by a Single Resistor
- Internal Thermal-Overload Protection
- RS-423-B Inputs and Outputs Designed to Withstand ±25 V
- ESD Protection Exceeds 2000 V Per MIL-STD-833C Method 3015
- LinBiCMOS[™] Process Technology

description

The SN75LBC786 is a monolithic quadruple RS-423-B driver and receiver with integrated-loopback function. The operation of the

DW PACKAGE (TOP VIEW) 28 7 2LB 3A [3Z **∏** 2 27 1 2Z 3LB **1** ₃ 26 2A 25 1 1LB 4A [4 4Z **∏** 5 24**∏** 1Z 4LB **∏** 6 23**∏** 1A 22 R_{WS} V_{SS} [] 7 GND [8 21 V_{DD} 4B [20 1 1Y 9 4Y **1** 10 19**∏** 1B 3B **∏** 11 18 2Y 17 1 2B 3Y [12 16 🛮 2C 3C **1** 13 4C **∏** 14 15**∏** 1C

SN75LBC786 is closely based on that of the SN75186. In normal operation, the device performs as four independent RS-423-B driver/receiver pairs designed to interface data-terminal equipment (DTE) with data circuit-terminating equipment (DCE). In loopback mode, the signal from each driver output is fed back via special circuitry into its associated receiver input, removing the need to locally disconnect cables and install a loopback connector. The receiver output signal is the same as the driver input signal.

The SN75LBC786 is characterized for operation over the temperature range of 0°C to 70°C.

FUNCTION TABLE

LOOPBACK	II.	INPUTS OUTP			PUTS
LB	Α	В	С	Z	Υ
нтт	LILI	L L H	H H L L	HHLL	H L H L
H H H	L H L	L L H	L L H	? ? ? ?	H L H L
L L	L H	X X	X X	L H	L L

H = high level, L = low level, X = irrelevant, ? = indeterminate

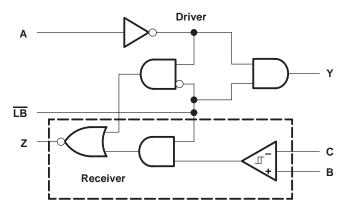


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logic diagram (positive logic) (each transceiver)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Positive supply voltage, V _{DD} (see Note 1)	
Negative supply voltage, V _{SS}	
Receiver input voltage range	–30 V to 30 V
Driver input voltage range	0.5 V to 5.75 V
Loopback input voltage range	0.5 V to 5.75 V
Driver output voltage range (supplies at 0 V)	30 V to 30 V
Driver output voltage range (supplies at ±12 V)	
Continuous power dissipation at (or below) T _A = 70°C	800 mW
Operating free-air temperature range, T _A	0°C to 70°C
Storage temperature range, T _{Stq}	–65°C to 150°C
Case temperature for 10 seconds	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltages are with respect to network ground terminal.

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V _{DD}		10.8	12	13.2	V
Supply voltage, V _{SS}		-10.8	-12	-13.2	V
High-level input voltage, VIH	Driver and loopback	2			V
Low-level input voltage, V _{IL}	Driver and loopback			0.8	V
High-level output current, IOH	Receiver			-4	mA
Low-level output current, IOL	Receiver			4	mA
Slew rate control resistor, RWS		20	82	820	kΩ
Operating free-air temperature, TA		0		70	°C



DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST CON	DITIONS	MIN	TYP	MAX	UNIT
Vон	High-level output voltage	Open circuit or RI =	Open circuit or RI = 450 Ω		5.5	6	V
VOL	Low-level output voltage	Open circuit or RI =	450 Ω	-6	-5.5	-4	V
lН	High-level input current	$V_{\parallel} = 2.4 \text{ V} - 5.5 \text{ V}$				100	μΑ
IIL	Low-level input current	V _I = 0 V - 0.8 V		-100			μΑ
likg	Output leakage current	$V_{DD} = V_{SS} = 0 V$	V _O = ±6 V	-100		100	μΑ
IOS(H)	High-level short-circuit output current	V _I = high,	VO = 0 V	15		45	mA
I _{OS(L)}	Low-level short-circuit output current	$V_{I} = low,$	VO = 0 V	-45		-15	mA
	Supply current (loopback off)	No load,	LB at 2 V		10	12	A
IDD		$RI = 450 \Omega$,	LB at 2 V		60	70	mA
I _{DD(LB)}	Supply current with loopback on	No load,	LB at 0.8 V		13	16	mA
	Complete support (leasth ask off)	No load,	LB at 2 V		-10	-12	A
ISS	Supply current (loopback off)	$RI = 450 \Omega$,	LB at 2 V		-60	-70	mA
I _{DD}	Supply current with loopback on	No load,	LB at 0.8 V		-13	-16	mA
LOOPBA	CK MODE			-			
	Output voltage (input either high or low)	$RI = >450 \Omega$,	V _{LB} = low	-6	-5.5	-4	V

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER	1	TEST CONDITI	ONS	MIN	TYP	MAX	UNIT
Transition time, tTLH (see Figure 1)				$RWS = 0 k\Omega$		1.5		
				$R_{WS} = 20 \text{ k}\Omega$	1.5	2.1	2.7	
	Transition time, low-to-high level output (see Figure 1)			RWS = $82 \text{ k}\Omega$	5	8	11	μs
	(6661 igure 1)			$R_{WS} = 820 \text{ k}\Omega$		80		
		RI = 450Ω , $C_L = 50 pF$,	$R_{WS} = 0 k\Omega$		1.5			
		$V_{WS} = 5 V$		$R_{WS} = 20 \text{ k}\Omega$	1.5	2.1	2.7	
tTHL	Transition time, high-to-low level output (see Figure 1)			RWS = $82 \text{ k}\Omega$	5	8	11	μs
(30	(See Figure 1)			$R_{WS} = 820 \text{ k}\Omega$		80		
SR	Output slew rate			$R_{WS} = 20 \text{ k}\Omega$			15	V/μs
t _{sk}	Output skew, tpHL - tpLH (see Figure 4)			$R_{WS} = 82 \text{ k}\Omega$			1	μs

RECEIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CO	MIN	TYP	MAX	UNIT	
\/	Receiver input threshold voltage	$V_{IT} = (V_{I+} - V_{I-})$		-200		200	m\/
VIT	(see Figure 5)	$V_{IT} = (V_{I+} - V_{I-})$ with 5	00-Ω series resistor	-400		400	mV
١.	Input current	V _I = 10 V	Other input to CND		1.3	3.25	mA
ij input	input current	V _I = -10 V	Other input to GND	-3.25	-1.3		IIIA
V _{hys}	Hysteresis voltage			20	40	150	mV
V	High-level output voltage (see Note 2)	$I_{O} = -20 \mu\text{A}$		3.5		5	V
VOH	High-level output voltage (see Note 2)	$I_O = -4 \text{ mA}$	2.4		5	V	
VOL	Low-level output voltage	I _O = 20 μA to 4 mA				0.4	V
los	RX short circuit current					50	mA
V_{ID}	Differential input voltage	Receiver inputs open circuit		1.6	2.1	2.6	V
Vofs	Fail safe output voltage	See Note 3		3.5			V

NOTES: 2. Device has an internal RX supply regulator. Maximum RX logic output voltage under no load is thus defined by an internal voltage value. This is nominally set to 4.5 V with a tolerance of $\pm 5\%$.

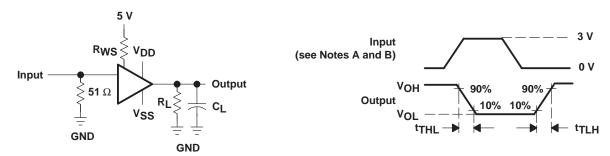
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	NOM	MAX	UNIT
tPLH	Propagation delay time, low-to-high (see Figure 2)		0.15 1			
tPHL	Propagation delay time, high-to-low (see Figure 2)	C ₁ = 50 pF		1	μs	
^t THL	Transition time, high-to-low (see Figure 3)	OL = 50 pr		20	200	no
tTLH	Transition time, low-to-high (see Figure 3)			20	200	ns



^{3.} One input at ground, other input open circuit, $I_O = -20 \mu A$, or both open circuit.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: $t_r \le 10$ nS, $t_f < 10$ nS, $Z_0 = 50$ Ω , PRR ≥ 5 kHz, duty cycle = 50%, $V_{max} = 3$ V, $V_{min} = 0$ V.

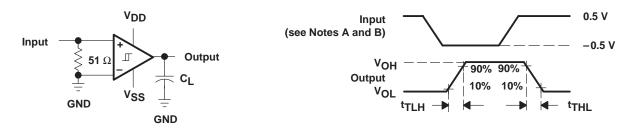
Figure 1. Driver Transition Times



NOTES: A. C_L includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: $t_{\Gamma} \le 10$ nS, $t_{f} < 10$ nS, $t_{Q} = 50$ Ω , PRR ≥ 5 kHz, duty cycle = 50%, $t_{Q} = 50$ V, $t_{Q} = 50$ V, $t_{Q} = 50$ V.

Figure 2. Receiver Propagation Delay Times

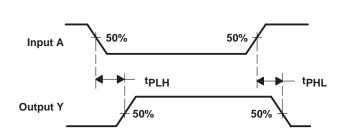


NOTES: A. C_L includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: $t_{\Gamma} \le 10$ nS, $t_{f} < 10$ nS, $t_{Q} = 50$ Ω , PRR ≥ 5 kHz, duty cycle = 50%, $t_{Q} = 50$ V, $t_{Q} = 50$ V, $t_{Q} = 50$ V.

Figure 3. Receiver Transition Times

PARAMETER MEASUREMENT INFORMATION



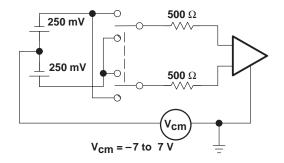


Figure 4. Skew Definition Times

Figure 5. Input Balance Test

PRINCIPLES OF OPERATION

In normal operation, the SN75LBC786 functions as four independent drivers and receivers. The loopback mode is disabled by maintaining a high logic level on the $\overline{\text{LB}}$ input. The receivers consist of differential comparators with hysteresis and resistive attenuation on the inputs. The resistive attenuation improves the input common-mode range and also provides additional protection from ESD and over-voltage stress. The differential and common-mode input impedance are sufficiently high to meet RS-423-B. The balance of the receiver input voltage current characteristics and bias voltage is such that the receiver remains in the intended binary state when a differential voltage of 500 mV is applied to the inputs through 500 Ω across the entire common-mode range (see Figure 5).

The drivers meet all RS-423-B specifications. In normal operation, the drivers have built-in current limits and thermal overload protection. Slew-rate controlling circuitry is included into the design that is adjusted to suit the application by means of an external resistor. The slew-rate controlling circuitry also has a default mode. If R_{WS} is shorted to 5 V externally, the transition time defaults to approximately 1.5 μ s. The receiver is compatible to the RS-232 with the use of external input resistors to meet the RS-232 input-resistance specification of 3 $k\Omega$ to 7 $k\Omega$.

Taking an individual \overline{LB} input low activates the loopback mode in the corresponding driver/receiver pair. This causes the output from that driver to be fed back to the input of its receiver through dedicated internal-loopback circuitry. Data from the receiver output can then be compared, by a communication system, with the data transmitted to the driver to determine if the functional operation of the driver and receiver together is correct.

In the loopback mode, external data at the input of the receiver is ignored and the driver does not transmit data onto the line. Extraneous data is prevented internally from being sent by the driver in the loopback mode by clamping its output to a level below the maximum interface voltage, -5 V, or the EIA-423-B marking state. Below this marking level, a reduced 1.5-V output amplitude is used at the driver output. This signal is detected by an on-chip loopback comparator and fed to the input stage of the receiver to complete the loop.

Line faults external to the SN75LBC786 are detected in addition to device failures. These line faults include short circuits to ground and to external supply voltages. The loopback mode should be entered only when the driver output is low, that is, the marking condition. It is recommended that loopback not be entered when the driver output is in a high state as this may cause a low-level, nondamaging oscillation at the driver output.





PACKAGE OPTION ADDENDUM

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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN75LBC786DW	OBSOLETE	SOIC	DW	28	TBD	Call TI	Call TI
SN75LBC786DWG4	OBSOLETE	SOIC	DW	28	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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